

STC OT391 Sensitive Gate Silicon Controlled Rectifier

Reverse Blocking Thyristor

PNPN device designed for line-powered general purpose applications such as relay and lamp drivers, small motor controls, gate drivers for larger thyristors, and sensing and detection circuits. Supplied in a cost effective plastic TO-92 package.

- Sensitive Gate Allows Direct Triggering by Microcontrollers and Other Logic Circuits
- On-State Current Rating of 0.8 Amperes RMS at 80°C
- Surge Current Capability 10 Amperes
- Immunity to dV/dt 20 V/µsec Minimum at 110°C
- Glass-Passivated Surface for Reliability and Uniformity
- Blocking Voltage to 600 Volts

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Peak Repetitive Off–State Voltage (Note 1.) (T _J = -40 to 110°C, Sine Wave, 50 to 60 Hz; Gate Open)	V _{DRM,} V _{RRM}	600	Volts
On-State RMS Current (T _C = 80°C) 180° Conduction Angles	I _{T(RMS)}	0.8	Amp
Peak Non-Repetitive Surge Current (1/2 Cycle, Sine Wave, 60 Hz, T _J = 25°C)	I _{TSM}	10	Amps
Circuit Fusing Consideration (t = 10 ms)	I ² t	0.415	A ² s
Forward Peak Gate Power $(T_A = 25^{\circ}C, \text{ Pulse Width } \leq 1.0 \mu\text{s})$	P _{GM}	0.1	Watt
Forward Average Gate Power (T _A = 25°C, t = 20 ms)	P _{G(AV)}	0.10	Watt
Forward Peak Gate Current $(T_A = 25^{\circ}C, \text{ Pulse Width } \leq 1.0 \mu\text{s})$	I _{GM}	1.0	Amp
Reverse Peak Gate Voltage $(T_A = 25^{\circ}C, \text{ Pulse Width } \leq 1.0 \mu\text{s})$	V_{GRM}	5.0	Volts
Operating Junction Temperature Range @ Rate V _{RRM} and V _{DRM}	TJ	-40 to 110	°C
Storage Temperature Range	T _{stg}	–40 to 150	°C

(1) VDRM and VRRM for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; however, positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant source such that the voltage ratings of the devices are exceeded.

SCR 0.8 AMPERES RMS 600 VOLTS





TO-92 (TO-226) CASE 029 STYLE 10

PIN ASSIGNMENT		
1	Cathode	
2	Gate	
3	Anode	

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THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance – Junction to Case – Junction to Ambient	R _{θJC} R _{θJA}	75 200	°C/W
Lead Solder Temperature (<1/16" from case, 10 secs max)	T _L	260	°C

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

ELECTRICAL CHARACTERISTICS (TC = 25 C di	ness otherwise neted,		1	_		
Characteristic		Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS						
Peak Repetitive Forward or Reverse Blocking Current (Note 1.) $(V_D = Rated \ V_{DRM} \ and \ V_{RRM}; \ R_{GK} = 1.0 \ k\Omega)$	T _C = 25°C T _C = 110°C	I _{DRM} , I _{RRM}	_ _	_ _	10 0.1	μA mA
ON CHARACTERISTICS						
Peak Forward On–State Voltage ^(*) (I _{TM} = 1.0 Amp Peak @ T _A = 25°C)		V_{TM}	_	_	1.3	Volts
Gate Trigger Current (Continuous dc) (Note 2.) (V _{AK} = 12 V, R _L = 100 Ohms)	T _C = 25°C	I _{GT}	-	6	8	μА
Holding Current (Note 2.) (V _{AK} = 12 V, I _{GT} = 0.5 mA)	$T_C = 25^{\circ}C$ $T_C = -40^{\circ}C$	lΗ	-	0.5 -	5.0 10	mA
Latch Current $(V_{AK} = 12 \text{ V}, I_{GT} = 0.5 \text{ mA}, R_{GK} = 1.0 \text{ k})$	$T_C = 25^{\circ}C$ $T_C = -40^{\circ}C$	ΙL	-	0.6 -	10 15	mA
Gate Trigger Voltage (Continuous dc) (Note 2.) (V _{AK} = 12 V, R _L = 100 Ohms, I _{GT} = 10 mA)	$T_C = 25^{\circ}C$ $T_C = -40^{\circ}C$	V_{GT}	-	0.5 -	0.52 1.2	Volts
DYNAMIC CHARACTERISTICS						
Critical Rate of Rise of Off–State Voltage $(V_D = Rated\ V_{DRM},\ Exponential\ Waveform,\ R_{GK} = 1$ $T_J = 110^{\circ}C)$	000 Ohms,	dV/dt	20	35	-	V/µs
Critical Rate of Rise of On–State Current (I _{PK} = 20 A; Pw = 10 μsec; diG/dt = 1.0 A/μsec, Igt = 20 mA)		di/dt	_	_	50	A/μs

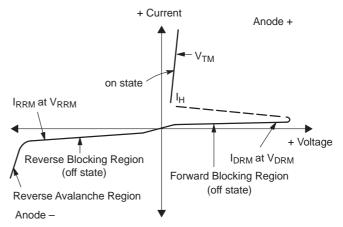
^{*}Indicates Pulse Test: Pulse Width ≤ 1.0 ms, Duty Cycle ≤ 1%.

 $[\]begin{array}{ll} \hbox{1.} & R_{GK} = 1000 \mbox{ Ohms included in measurement.} \\ \hbox{2.} & \mbox{Does not include } R_{GK} \mbox{ in measurement.} \\ \end{array}$

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Voltage Current Characteristic of SCR

Symbol	Parameter
V _{DRM}	Peak Repetitive Off State Forward Voltage
I _{DRM}	Peak Forward Blocking Current
V _{RRM}	Peak Repetitive Off State Reverse Voltage
I _{RRM}	Peak Reverse Blocking Current
V_{TM}	Peak on State Voltage
I _H	Holding Current



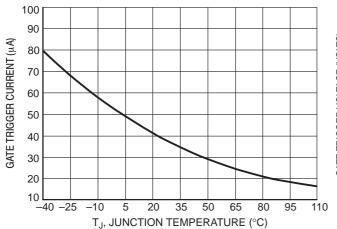


Figure 1. Typical Gate Trigger Current versus Junction Temperature

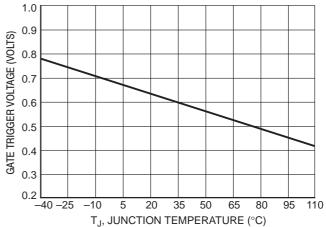


Figure 2. Typical Gate Trigger Voltage versus
Junction Temperature

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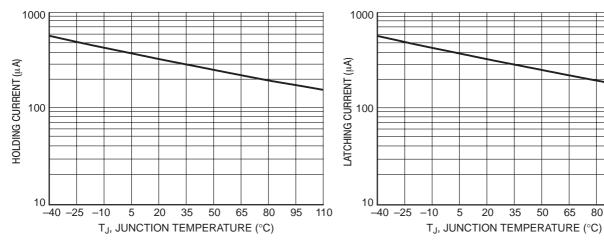


Figure 3. Typical Holding Current versus Junction Temperature

Figure 4. Typical Latching Current versus Junction Temperature

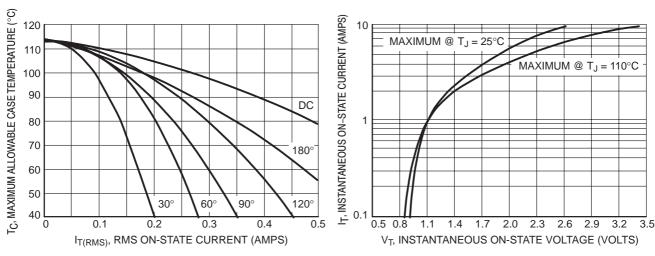


Figure 5. Typical RMS Current Derating

Figure 6. Typical On-State Characteristics